IPC ASSOCIATION CONNECT ELECTRONICS INDUSTR	© Copyright 2005. I	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.			der both	This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.									
752-21.1		IPC Web Site for Information on IPC-1752 Standard Form Typ http://www.ipc.org/IPC-175x Distribute				*	Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Mater					ials and Mfg Information			
upplier Infor	mation														
Company name*			Company unique ID			J	Unique ID Authority				Response Date*				
nsemi											2024-05-19				
Contact Name		Title - Contact			I	Phone - Contact*				Email - Contact*					
Product-Env-Stev	wards		Product Enviro Compliance]	NA				Product-Env-Stewards@onsemi.com				
uthorized Repre	sentative*	Title - Representative			I	Phone - Representative*			Email - Representative*						
Product-Env-Stev	wards		Product Enviro Compliance]	NA				Product-Env-Stewards@onsemi.com				
Reques	ster Item Number	Mfr Item	Number	Mfr Item Name			Effective Date	Version	sion Manufacturing Site		V	Veight*	UOM	Unit Type	
		ESD6100 ASIP USB OTG		ASIP USB OTG LO	OW CAP ESD	D 2024-05-19		C	CNQ		.8819	mg	Each		
Ianufacturing	g Proccess Informa	ntion											·		
Terminal Plating / Grid Array Material Terminal Base			Base Alloy J-STD-020 MSL Rating Peal				eak Process Body Temperature Max Time at Peak Temperature Number of Reflow Cycles								
SnAgCu			CU Alloy 1				260 C 30			seconds 3					
omments															
vel 1 - maximum	time at peak temperat	ure during sol	dering is 10-3	0 seconds											
or more informa	tion regarding material	composition	please refer to	page 3											

RoHS Material Composition Declaration			Declaration Type *	Detail	ed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).											
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on informationprovided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusivesource of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form. In the absence of such written agreement, the warranty rights and/or remedies of Supplier's Sta											
RoHS Declaration * 1 - Item	(s) does not contain RoHS restricted substar	nces per the definition above	Supplier A	cceptance *	Accepted						
Exemption: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.											
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
		e "Accepted" on the Supplier Acceptance	drop-down. This will display the signature a	rea. Digitally sign t	the declaration (if required by the						

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	0.622	mg	Supplier	Silicon (Si)	7440-21-3		0.622	mg
Protection coat	0.01	mg		Polyimide	proprietary data		0.01	mg
Solder Ball	0.242	mg	Supplier	Silver (Ag)	7440-22-4		0.0024	mg
			Supplier	Tin (Sn)	7440-31-5		0.2384	mg
			Supplier	Copper (Cu)	7440-50-8		0.0012	mg
Under Bump Metal	0.0079	mg	Supplier	Titanium (Ti)	7440-32-6		0	mg
			Supplier	Copper (Cu)	7440-50-8		0.0079	mg